L Number	Hits	Search Text	DB	Time stamp
1	19	("3870445" "5371450" "5912025" "5632222" "4131596") .pn.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/25 13:27
2	19	("3870445" "5371450" "5912025" "5362222" "4131596") .pn.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/25 13:28
-	164	73/856.ccls.	USPAT	2001/02/26 09:32
-	10	73/856.ccls. and mold	USPAT	2001/02/26 09:38
-	5	73/856.ccls. and (mold molding) and (injection inject pressure)	USPAT	2001/02/26 09:36
-	40553	(injection pressure) and (molding mold) and (device apparatus machine).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/26 09:42
-	9162	(injection pressure) and (molding mold) and (device apparatus machine) and (control controls).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/26 15:12
-	21	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls) and sensor and switch).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 13:34
-	4	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls) and (force pressure strain) near4 sensor and switch).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/26 10:00
-	10	(injection pressure) and (molding mold) and (device apparatus machine) and (control controls)and (subtractor substractor).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/27 13:41
-	2	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls)and (subtractor substractor)and (clamp clamping)).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/27 13:45
-	1	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls)and (subtractor substractor)and (clamp clamping)and sensor).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/27 13:45
-	26	("4131596" "4506321" "4714867" "5274316" "5313151" "5341452" "5362222" "5444341" "5583411").pn.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/23 17:05
-	27	("3864557" "3870445" "3878372" "3937776" "4094940" "4311446" "5232714" "5237509").pn.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/23 17:06
-	1	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls) and force near2 sensor and switch).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:01
-	1	((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls) and force near2 sensor).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:41
-	1	((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls controller) and force near2 sensor).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:06
-	17	425/$6.ccls. and ((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls) and force near2 sensor)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:44
-	10	425/$6.ccls. and ((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls) and force near sensor)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:49

-	1	425/$6.ccls. and ((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls) and force near sensor) and platen	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:53
-	0	425/$6.ccls. and ((injection pressure) near2 (molding mold) and (control controls) and ((force near sensor) near4 platen))	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:56
-	0	425/$6.ccls. and ((injection pressure) near2 (molding mold) and (control controls) and ((force near sensor) near6 platen))	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:56
-	1	425/$6.ccls. and ((injection pressure) near2 (molding mold) and (control controls) and ((force near sensor) and platen))	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:57
-	0	425/$6.ccls. and ((injection pressure) near2 (molding mold) and (clamp$4) near2 ((force near sensor) and platen))	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:58
-	1	425/$6.ccls. and ((injection pressure) near2 (molding mold) and (clamp$4) and ((force near sensor) and platen))	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:58
-	0	425/$6.ccls. and ((injection pressure) near2 (molding mold) and (clamp$4) near6 ((force near sensor) and platen))	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:59
-	88	425/$6.ccls. and ((injection pressure) near2 (molding mold) and (clamp$4) near6 force and sensor and platen)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:59
-	4	425/$6.ccls. and ((injection pressure) near2 (molding mold) and (clamp$4) near6 force near4 sensor and platen)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 15:06
-	4	425/$6.ccls. and ((injection pressure) near2 (molding mold) and (clamp$4 near6 force) and (force near4 sensor) and platen)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/25 13:17